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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	750
Number of Logic Elements/Cells	6000
Total RAM Bits	56320
Number of I/O	190
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-6se-5fn256c

Features

- **High Logic Density for System Integration**
 - 6K to 95K LUTs
 - 90 to 583 I/Os
- **Embedded SERDES (LatticeECP2M Only)**
 - Data Rates 250 Mbps to 3.125 Gbps
 - Up to 16 channels per device
PCI Express, Ethernet (1GbE, SGMII), OBSAI, CPRI and Serial RapidIO.
- **sysDSP™ Block**
 - 3 to 42 blocks for high performance multiply and accumulate
 - Each block supports
 - One 36x36, four 18x18 or eight 9x9 multipliers
- **Flexible Memory Resources**
 - 55Kbits to 5308Kbits sysMEM™ Embedded Block RAM (EBR)
 - 18Kbit block
 - Single, pseudo dual and true dual port
 - Byte Enable Mode support
 - 12K to 202Kbits distributed RAM
 - Single port and pseudo dual port
- **sysCLOCK Analog PLLs and DLLs**
 - Two GPLLs and up to six SPLLs per device
 - Clock multiply, divide, phase & delay adjust
 - Dynamic PLL adjustment
 - Two general purpose DLLs per device
- **Pre-Engineered Source Synchronous I/O**
 - DDR registers in I/O cells
 - Dedicated gearing logic
 - Source synchronous standards support
 - SPI4.2, SF14 (DDR Mode), XGMII
 - High Speed ADC/DAC devices
 - Dedicated DDR and DDR2 memory support
 - DDR1: 400 (200MHz) / DDR2: 533 (266MHz)
 - Dedicated DQS support
- **Programmable sysI/O™ Buffer Supports Wide Range Of Interfaces**
 - LVTTTL and LVCMOS 33/25/18/15/12
 - SSTL 3/2/18 I, II
 - HSTL15 I and HSTL18 I, II
 - PCI and Differential HSTL, SSTL
 - LVDS, RSDS, Bus-LVDS, MLVDS, LVPECL
- **Flexible Device Configuration**
 - 1149.1 Boundary Scan compliant
 - Dedicated bank for configuration I/Os
 - SPI boot flash interface
 - Dual boot images supported
 - TransFR™ I/O for simple field updates
 - Soft Error Detect macro embedded
- **Optional Bitstream Encryption (LatticeECP2/M “S” Versions Only)**
- **System Level Support**
 - ispTRACY™ internal logic analyzer capability
 - On-chip oscillator for initialization & general use
 - 1.2V power supply

Table 1-1. LatticeECP2 (Including “S-Series”) Family Selection

Device	ECP2-6	ECP2-12	ECP2-20	ECP2-35	ECP2-50	ECP2-70
LUTs (K)	6	12	21	32	48	68
Distributed RAM (Kbits)	12	24	42	64	96	136
EBR SRAM (Kbits)	55	221	276	332	387	1032
EBR SRAM Blocks	3	12	15	18	21	60
sysDSP Blocks	3	6	7	8	18	22
18x18 Multipliers	12	24	28	32	72	88
GPLL + SPLL + DLL	2+0+2	2+0+2	2+0+2	2+0+2	2+2+2	2+4+2
Maximum Available I/O	190	297	402	450	500	583
Packages and I/O Combinations						
144-pin TQFP (20 x 20 mm)	90	93				
208-pin PQFP (28 x 28 mm)		131	131			
256-ball fpBGA (17 x 17 mm)	190	193	193			
484-ball fpBGA (23 x 23 mm)		297	331	331	339	
672-ball fpBGA (27 x 27 mm)			402	450	500	500
900-ball fpBGA (31 x 31 mm)						583

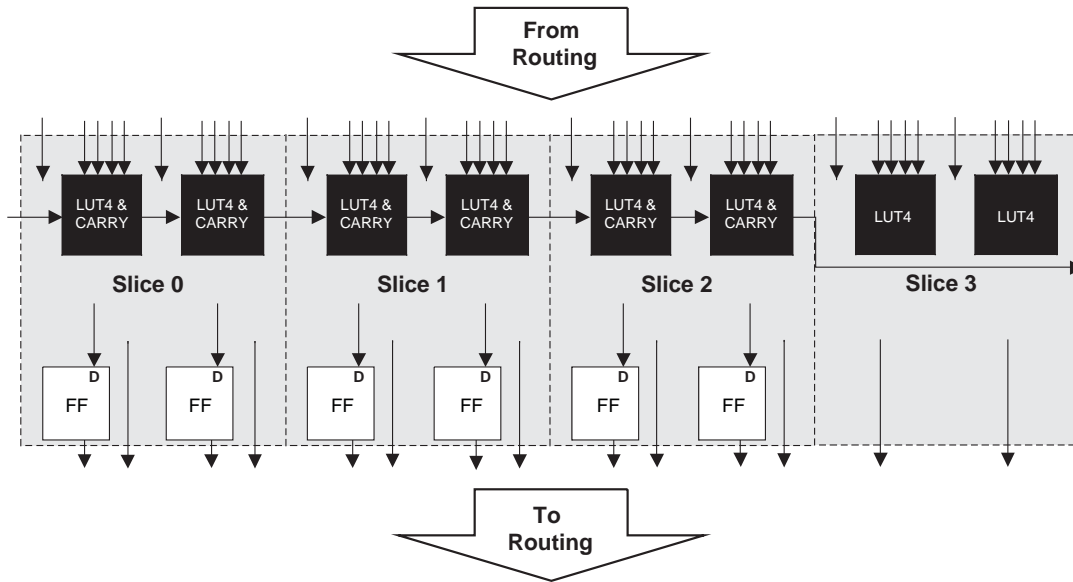
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PFU Blocks

The core of the LatticeECP2/M device consists of PFU blocks, which are provided in two forms, the PFU and PFF. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

Slice 0 through Slice 2 contain two LUT4s feeding two registers, whereas Slice 3 contains two LUT4s only. For PFUs, Slice 0 and Slice 2 can also be configured as distributed memory, a capability not available in the PFF. Table 2-1 shows the capability of the slices in both PFF and PFU blocks along with the operation modes they enable. In addition, each PFU contains some logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Table 2-1. Resources and Modes Available per Slice

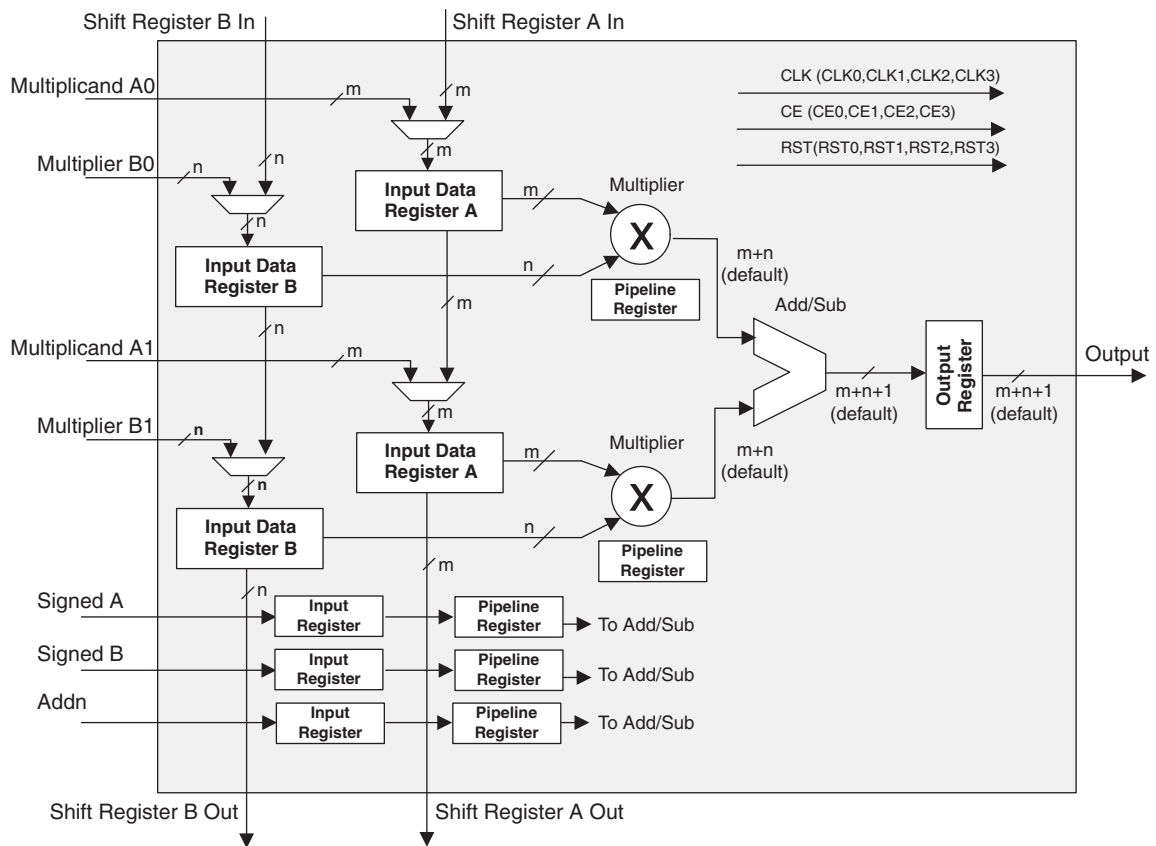
Slice	PFU BLock		PFF Block	
	Resources	Modes	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s	Logic, ROM	2 LUT4s	Logic, ROM

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 13 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

MULTADDSUB sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and A2. The user can enable the input, output and pipeline registers. Figure 2-25 shows the MULTADDSUB sysDSP element.

Figure 2-25. MULTADDSUB



LatticeECP2/M DSP Performance

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP2/M family.

Table 2-11. DSP Performance

Device	DSP Block	DSP Performance GMAC
ECP2-6	3	3.9
ECP2-12	6	7.8
ECP2-20	7	9.1
ECP2-35	8	10.4
ECP2-50	18	23.4
ECP2-70	22	28.6
ECP2M20	6	7.8
ECP2M35	8	10.4
ECP2M50	22	28.6
ECP2M70	24	31.2
ECP2M100	42	54.6

For further information about the sysDSP block, please see the list of additional technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O buffers as shown in Figure 2-28. The PIO Block supplies the output data (DO) and the tri-state control signal (TO) to the sysI/O buffer and receives input from the buffer. Table 2-12 provides the PIO signal list.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, [LatticeECP2/M sysCONFIG Usage Guide](#) for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. Decryption Support

LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. TransFR (Transparent Field Reconfiguration)

TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#), for details.

3. Dual Boot Image Support

Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	210	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
$C1^4$	I/O Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
$C2^4$	Dedicated Input Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF} maximum leakage = 25uA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, $f = 1.0MHz$.

sys/I/O Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}^1 (mA)	I_{OH}^1 (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35 V_{CCIO}$	$0.65 V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35 V_{CCIO}$	$0.65 V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2	-0.3	$0.35 V_{CC}$	$0.65 V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3 V_{CCIO}$	$0.5 V_{CCIO}$	3.6	$0.1 V_{CCIO}$	$0.9 V_{CCIO}$	1.5	-0.5
SSTL3 Class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 Class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 Class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
							12	-12
SSTL2 Class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
							20	-20
SSTL18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
SSTL18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.28	$V_{CCIO} - 0.28$	8	-8
							11	-11
HSTL Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	4	-4
							8	-8
HSTL18 Class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
							12	-12
HSTL18 Class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$, where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

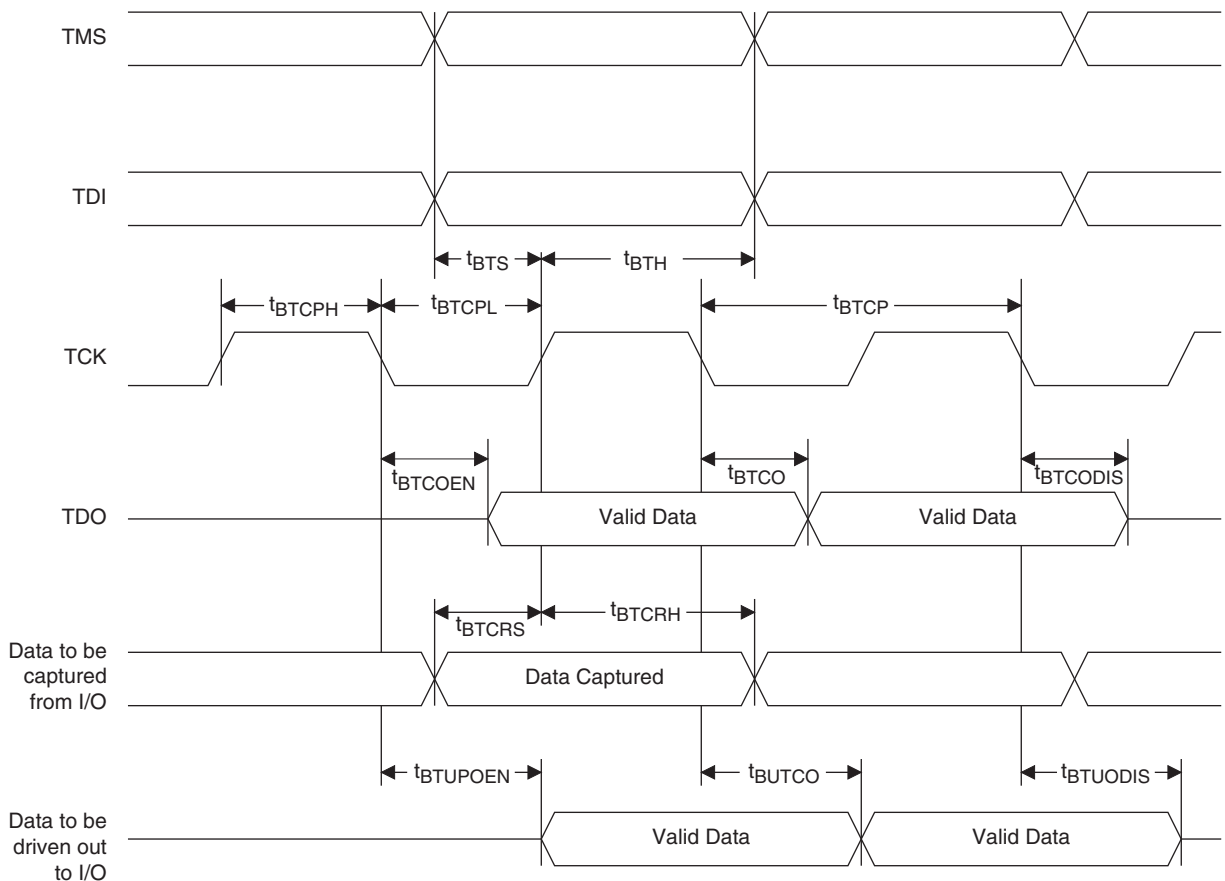
JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
f_{MAX}	TCK clock frequency	—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	8	—	ns
t_{BTH}	TCK [BSCAN] hold time	10	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	mV/ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Timing v.A 0.11

Figure 3-21. JTAG Port Timing Waveforms



LatticeECP2 Pin Information Summary, LFE2-6 and LFE2-12 (Cont.)

Pin Type		LFE2-6		LFE2-12			
		144 TQFP	256 fpBGA	144 TQFP	208 PQFP	256 fpBGA	484 fpBGA
Available DDR-Interfaces per I/O Bank ¹	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	1	0	0	1	1
	Bank3	0	0	0	0	0	0
	Bank4	0	2	0	0	2	3
	Bank5	0	1	0	0	1	3
	Bank6	0	1	0	0	1	1
	Bank7	0	1	0	0	1	1
	Bank8	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	0	0	0	0	0
	Bank3	0	0	0	0	0	0
	Bank4	18	32	18	19	32	46
	Bank5	8	14	10	18	17	46
	Bank6	0	0	0	0	0	0
	Bank7	0	0	0	0	0	0
	Bank8	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LatticeECP2M Pin Information Summary, LFE2M20 and LFE2M35

Pin Type		LFE2M20		LFE2M35		
		256 fpBGA	484 fpBGA	256 fpBGA	484 fpBGA	672 fpBGA
Single Ended User I/O		140	304	140	303	410
Differential Pair User I/O		70	152	70	151	199
Configuration	TAP Pins	5	5	5	5	5
	Muxed Pins	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7
Non Configuration	Muxed Pins	64	84	60	84	89
	Dedicated Pins	3	3	3	3	3
VCC		6	16	6	16	29
VCCAUX		4	8	4	8	17
VCCPLL		1	4	1	4	8
VCCIO	Bank0	1	4	1	4	5
	Bank1	1	3	1	3	4
	Bank2	2	4	2	4	5
	Bank3	2	4	2	4	5
	Bank4	2	4	2	4	4
	Bank5	2	4	2	4	5
	Bank6	2	4	2	4	5
	Bank7	2	4	2	4	5
	Bank8	1	2	1	2	2
GND, GND0 to GND7		22	57	22	57	80
NC		17	11	17	12	37
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	0/0	36/18	0/0	36/18	63/31
	Bank1	0/0	18/9	0/0	18/9	18/9
	Bank2	14/7	30/15	14/7	30/15	50/25
	Bank3	16/8	36/18	16/8	36/18	43/21
	Bank4	32/16	62/31	32/16	62/31	50/21
	Bank5	20/10	28/14	20/10	28/14	60/30
	Bank6	16/8	40/20	16/8	39/19	52/25
	Bank7	28/14	40/20	28/14	40/20	60/30
	Bank8	14/7	14/7	14/7	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0
	Bank2 (Right Edge)	3	7	3	7	12
	Bank3 (Right Edge)	4	9	4	9	11
	Bank4 (Bottom Edge)	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0
	Bank6 (Left Edge)	4	10	4	10	14
	Bank7 (Left Edge)	7	10	7	10	15
	Bank8 (Right Edge)	0	0	0	0	0

**LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA
 (Cont.)**

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D15	PT52A	1		T	PT61A	1		T
E15	PT51B	1		C	PT60B	1		C
F15	PT51A	1		T	PT60A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
B15	PT49B	1		C	PT58B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
A15	PT49A	1		T	PT58A	1		T
B14	PT48B	1		C	PT57B	1		C
A14	PT48A	1		T	PT57A	1		T
D14	PT46B	1		C	PT55B	1		C
C13	PT46A	1		T	PT55A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
E14	PT45B	1		C	PT54B	1		C
F14	PT45A	1		T	PT54A	1		T
A13	PT44B	1		C	PT53B	1		C
B13	PT44A	1		T	PT53A	1		T
VCCIO	VCCIO1	1			VCCIO	1		
E13	PT43B	1		C	PT52B	1		C
D13	PT43A	1		T	PT52A	1		T
E12	PT42B	1		C	PT51B	1		C
D12	PT42A	1		T	PT51A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
A12	PT40B	1		C	PT49B	1		C
A11	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO	1		
B12	PT39B	1	PCLKC1_0	C	PT48B	1	PCLKC1_0	C
C12	PT39A	1	PCLKT1_0	T	PT48A	1	PCLKT1_0	T
F12	XRES	1			XRES	1		
B10	PT37B	0	PCLKC0_0	C	PT46B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	0		
B11	PT37A	0	PCLKT0_0	T	PT46A	0	PCLKT0_0	T
A10	PT36B	0		C	PT45B	0		C
A9	PT36A	0		T	PT45A	0		T
C11	PT35B	0		C	PT44B	0		C
VCCIO	VCCIO0	0			VCCIO	0		
C10	PT35A	0		T	PT44A	0		T
E11	PT34B	0		C	PT43B	0		C
F11	PT34A	0		T	PT43A	0		T
A8	PT33B	0		C	PT42B	0		C
A7	PT33A	0		T	PT42A	0		T
B8	PT32B	0		C	PT41B	0		C
GNDIO	GNDIO0	-			GNDIO0	0		
B9	PT32A	0		T	PT41A	0		T
VCCIO	VCCIO0	0			VCCIO	0		
B7	PT30B	0		C	PT39B	0		C
A6	PT30A	0		T	PT39A	0		T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7/LDQ6	T (LVDS)*
D1	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7/LDQ6	C (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
F6	PL3A	7		T	PL3A	7	LDQ6	T
F5	PL3B	7		C	PL3B	7	LDQ6	C
VCCIO	VCCIO7	7			VCCIO7	7		
E4	NC	-			PL4A	7	LDQ6	T (LVDS)*
E3	NC	-			PL4B	7	LDQ6	C (LVDS)*
E2	NC	-			PL5A	7	LDQ6	T
E1	NC	-			PL5B	7	LDQ6	C
GND	GNDIO7	-			GNDIO7	-		
H6	NC	-			PL6A	7	LDQS6	T (LVDS)*
H5	NC	-			PL6B	7	LDQ6	C (LVDS)*
F2	NC	-			PL7A	7	LDQ6	T
VCCIO	VCCIO7	7			VCCIO7	7		
F1	NC	-			PL7B	7	LDQ6	C
H8	NC	-			PL8A	7	LDQ6	T (LVDS)*
J9	NC	-			PL8B	7	LDQ6	C (LVDS)*
G4	NC	-			PL9A	7	LDQ6	T
GND	GNDIO7	-			GNDIO7	-		
G3	NC	-			PL9B	7	LDQ6	C
H7	PL4A	7	LDQ8	T (LVDS)*	PL10A	7	LDQ14	T (LVDS)*
J8	PL4B	7	LDQ8	C (LVDS)*	PL10B	7	LDQ14	C (LVDS)*
G2	PL5A	7	LDQ8	T	PL11A	7	LDQ14	T
G1	PL5B	7	LDQ8	C	PL11B	7	LDQ14	C
H3	PL6A	7	LDQ8	T (LVDS)*	PL12A	7	LDQ14	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO7	7		
H4	PL6B	7	LDQ8	C (LVDS)*	PL12B	7	LDQ14	C (LVDS)*
J5	PL7A	7	LDQ8	T	PL13A	7	LDQ14	T
J4	PL7B	7	LDQ8	C	PL13B	7	LDQ14	C
J3	PL8A	7	LDQS8	T (LVDS)*	PL14A	7	LDQS14	T (LVDS)*
GND	GNDIO7	-			GNDIO7	-		
K4	PL8B	7	LDQ8	C (LVDS)*	PL14B	7	LDQ14	C (LVDS)*
H1	PL9A	7	LDQ8	T	PL15A	7	LDQ14	T
H2	PL9B	7	LDQ8	C	PL15B	7	LDQ14	C
VCCIO	VCCIO7	7			VCCIO7	7		
K6	PL10A	7	LDQ8	T (LVDS)*	PL16A	7	LDQ14	T (LVDS)*
K7	PL10B	7	LDQ8	C (LVDS)*	PL16B	7	LDQ14	C (LVDS)*
J1	PL11A	7	LDQ8	T	PL17A	7	LDQ14	T
J2	PL11B	7	LDQ8	C	PL17B	7	LDQ14	C
GND	GNDIO7	-			GNDIO7	-		
VCCIO	VCCIO7	7			VCCIO7	7		
K3	NC	-			NC	-		
K2	NC	-			NC	-		
GND	GNDIO7	-			GNDIO7	-		
K1	NC	-			NC	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AD2	PL90B	6	LDQ88	C (LVDS)*
AD7	PL91A	6	LDQ88	T
GND	GNDIO6	-		
AB9	PL91B	6	LDQ88	C
AD5	TCK	-		
AE7	TDI	-		
AD4	TMS	-		
AA9	TDO	-		
AD3	VCCJ	-		
AC8	PB2A	5	VREF2_5/BDQ6	T
AE8	PB2B	5	VREF1_5/BDQ6	C
AD8	PB3A	5	BDQ6	T
AF8	PB3B	5	BDQ6	C
AG7	PB4A	5	BDQ6	T
VCCIO	VCCIO5	5		
AH7	PB4B	5	BDQ6	C
AC9	PB5A	5	BDQ6	T
AE9	PB5B	5	BDQ6	C
AD9	PB6A	5	BDQS6	T
GND	GNDIO5	-		
AF9	PB6B	5	BDQ6	C
AB10	PB7A	5	BDQ6	T
AA10	PB7B	5	BDQ6	C
AJ7	PB8A	5	BDQ6	T
VCCIO	VCCIO5	5		
AK7	PB8B	5	BDQ6	C
AC10	PB9A	5	BDQ6	T
AE10	PB9B	5	BDQ6	C
AJ8	PB10A	5	BDQ6	T
GND	GNDIO5	-		
AK8	PB10B	5	BDQ6	C
AF6	PB11A	5	BDQ15	T
AF7	PB11B	5	BDQ15	C
AG5	PB12A	5	BDQ15	T
AH5	PB12B	5	BDQ15	C
AG6	PB13A	5	BDQ15	T
AH6	PB13B	5	BDQ15	C
VCCIO	VCCIO5	5		
AJ4	PB14A	5	BDQ15	T
AK4	PB14B	5	BDQ15	C
GND	GNDIO5	-		
AJ5	PB15A	5	BDQS15	T
AK5	PB15B	5	BDQ15	C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AB24	PR87B	8	D3	C
GND	GNDIO4	-		
AB23	PR87A	8	D4	T
AB25	PR86B	8	D5	C
AB26	PR86A	8	D6	T
AC27	PR85B	8	D7/SPID0	C
VCCIO	VCCIO8	8		
AB27	PR85A	8	DI/CSSPION	T
AD29	PR84B	8	DOUT/CSON	C
AD30	PR84A	8	BUSY/SISPI	T
AA25	PR83B	3	RDQ80	C
GND	GNDIO3	-		
AA23	PR83A	3	RDQ80	T
AC29	PR82B	3	RDQ80	C (LVDS)*
AC30	PR82A	3	RDQ80	T (LVDS)*
AA26	PR81B	3	RDQ80	C
VCCIO	VCCIO3	3		
AA24	PR81A	3	RDQ80	T
AB29	PR80B	3	RDQ80	C (LVDS)*
AB30	PR80A	3	RDQS80	T (LVDS)*
GND	GNDIO3	-		
Y23	PR79B	3	RDQ80	C
Y25	PR79A	3	RDQ80	T
AA27	PR78B	3	RDQ80	C (LVDS)*
AA28	PR78A	3	RDQ80	T (LVDS)*
VCCIO	VCCIO3	3		
Y24	PR77B	3	RLM0_GPLL_C_FB_A/RDQ80	C
Y26	PR77A	3	RLM0_GPLLT_FB_A/RDQ80	T
AA29	PR76B	3	RLM0_GPLL_C_IN_A**/RDQ80	C (LVDS)*
AA30	PR76A	3	RLM0_GPLLT_IN_A**/RDQ80	T (LVDS)*
R22	RLM0_PLLCAP	3		
W23	PR74B	3	RLM0_GDLL_C_FB_A/RDQ71	C
W25	PR74A	3	RLM0_GDLLT_FB_A/RDQ71	T
GND	GNDIO3	-		
Y27	PR73B	3	RLM0_GDLL_C_IN_A**/RDQ71	C (LVDS)*
Y28	PR73A	3	RLM0_GDLLT_IN_A**/RDQ71	T (LVDS)*
W24	PR72B	3	RDQ71	C
W26	PR72A	3	RDQ71	T
VCCIO	VCCIO3	3		
Y29	PR71B	3	RDQ71	C (LVDS)*
Y30	PR71A	3	RDQS71	T (LVDS)*
V25	PR70B	3	RDQ71	C
GND	GNDIO3	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
U10	VCCIO6	6		
U9	VCCIO6	6		
V10	VCCIO6	6		
W10	VCCIO6	6		
W9	VCCIO6	6		
Y9	VCCIO6	6		
L10	VCCIO7	7		
L9	VCCIO7	7		
M10	VCCIO7	7		
N10	VCCIO7	7		
P10	VCCIO7	7		
R10	VCCIO7	7		
AA21	VCCIO8	8		
Y21	VCCIO8	8		
AA15	VCCAUX	-		
AB11	VCCAUX	-		
AB19	VCCAUX	-		
AB20	VCCAUX	-		
J11	VCCAUX	-		
J12	VCCAUX	-		
J19	VCCAUX	-		
K19	VCCAUX	-		
L22	VCCAUX	-		
M9	VCCAUX	-		
N9	VCCAUX	-		
P21	VCCAUX	-		
P9	VCCAUX	-		
T10	VCCAUX	-		
T21	VCCAUX	-		
V9	VCCAUX	-		
W22	VCCAUX	-		
A1	GND	-		
A30	GND	-		
AC28	GND	-		
AC3	GND	-		
AH13	GND	-		
AH18	GND	-		
AH23	GND	-		
AH28	GND	-		
AH3	GND	-		
AH8	GND	-		
AK1	GND	-		
AK30	GND	-		

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA
(Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
T17	PR51A	8	D2***	T	PR66A	8	D2***	T
T22	PR50B	8	D3***	C	PR65B	8	D3***	C
GNDIO	GNDIO8	-			GNDIO8	-		
R22	PR50A	8	D4***	T	PR65A	8	D4***	T
T15	PR49B	8	D5***	C	PR64B	8	D5***	C
R17	PR49A	8	D6***	T	PR64A	8	D6***	T
T20	PR48B	8	D7/SPID0***	C	PR63B	8	D7/SPID0***	C
VCCIO	VCCIO8	8			VCCIO8	8		
T21	PR48A	8	DI/CSSPI0N***	T	PR63A	8	DI/CSSPI0N***	T
R21	PR47B	8	DOU/CSON/CSSPI1N***	C	PR62B	8	DOU/CSON/CSSPI1N***	C
R20	PR47A	8	BUSY/SISPI***	T	PR62A	8	BUSY/SISPI***	T
R16	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
R18	PR45B	3	RLM0_GDLLC_FB_A	C	PR60B	3	RLM0_GDLLC_FB_A/RDQ57	C
GNDIO	GNDIO3	-			GNDIO3	-		
R19	PR45A	3	RLM0_GDLLT_FB_A	T	PR60A	3	RLM0_GDLLT_FB_A/RDQ57	T
P22	PR44B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR59B	3	RLM0_GDLLC_IN_A**/RDQ57	C (LVDS)*
P21	PR44A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR59A	3	RLM0_GDLLT_IN_A**/RDQ57	T (LVDS)*
P16	PR43B	3	RLM0_GPLLC_IN_A**	C	PR58B	3	RLM0_GPLLC_IN_A**/RDQ57	C
VCCIO	VCCIO3	3			VCCIO3	3		
P17	PR43A	3	RLM0_GPLLT_IN_A**	T	PR58A	3	RLM0_GPLLT_IN_A**/RDQ57	T
P20	PR42B	3	RLM0_GPLLC_FB_A	C (LVDS)*	PR57B	3	RLM0_GPLLC_FB_A/RDQ57	C (LVDS)*
P19	PR42A	3	RLM0_GPLLT_FB_A	T (LVDS)*	PR57A	3	RLM0_GPLLT_FB_A/RDQS57****	T (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
-	-	-			VCCIO3	3		
P18	PR41B	3	RDQ38	C	PR51B	3	RDQ48	C
N16	PR41A	3	RDQ38	T	PR51A	3	RDQ48	T
GNDIO	GNDIO3	-			GNDIO3	-		
N22	PR40B	3	RDQ38	C (LVDS)*	PR50B	3	RDQ48	C (LVDS)*
N21	PR40A	3	RDQ38	T (LVDS)*	PR50A	3	RDQ48	T (LVDS)*
N17	PR39B	3	RDQ38	C	PR49B	3	RDQ48	C
N18	PR39A	3	RDQ38	T	PR49A	3	RDQ48	T
VCCIO	VCCIO3	3			VCCIO3	3		
M22	PR38B	3	RDQ38	C (LVDS)*	PR48B	3	RDQ48	C (LVDS)*
M21	PR38A	3	RDQS38	T (LVDS)*	PR48A	3	RDQS48	T (LVDS)*
M16	PR37B	3	RDQ38	C	PR47B	3	RDQ48	C
GNDIO	GNDIO3	-			GNDIO3	-		
M17	PR37A	3	RDQ38	T	PR47A	3	RDQ48	T
M20	PR36B	3	RDQ38	C (LVDS)*	PR46B	3	RDQ48	C (LVDS)*
M19	PR36A	3	RDQ38	T (LVDS)*	PR46A	3	RDQ48	T (LVDS)*
M18	PR35B	3	RDQ38	C	PR45B	3	RDQ48	C
VCCIO	VCCIO3	3			VCCIO3	3		
L16	PR35A	3	RDQ38	T	PR45A	3	RDQ48	T
L22	PR34B	3	RDQ38	C (LVDS)*	PR44B	3	RDQ48	C (LVDS)*
L21	PR34A	3	RDQ38	T (LVDS)*	PR44A	3	RDQ48	T (LVDS)*
K22	PR32B	3	RLM1_SPLLC_FB_A	C	PR42B	3	RLM2_SPLLC_FB_A	C
VCCIO	VCCIO3	3			VCCIO3	3		
K21	PR32A	3	RLM1_SPLLT_FB_A	T	PR42A	3	RLM2_SPLLT_FB_A	T
L17	PR31B	3	RLM1_SPLLC_IN_A	C (LVDS)*	PR41B	3	RLM2_SPLLC_IN_A	C (LVDS)*

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO7	-		
L1	PL36A	7	LDQS36	T (LVDS)*
L2	PL36B	7	LDQ36	C (LVDS)*
M7	PL37A	7	LDQ36	T
VCCIO	VCCIO7	7		
L5	PL37B	7	LDQ36	C
L3	PL38A	7	LDQ36	T (LVDS)*
L4	PL38B	7	LDQ36	C (LVDS)*
M1	PL39A	7	PCLKT7_0/LDQ36	T
GNDIO	GNDIO7	-		
M2	PL39B	7	PCLKC7_0/LDQ36	C
M6	PL41A	6	PCLKT6_0	T (LVDS)*
M5	PL41B	6	PCLKC6_0	C (LVDS)*
M3	PL42A	6	VREF2_6	T
M4	PL42B	6	VREF1_6	C
VCCIO	VCCIO6	6		
N7	PL45A	6	LLM3_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO6	-		
N6	PL45B	6	LLM3_SPLLC_IN_A	C (LVDS)*
N1	PL46A	6	LLM3_SPLLT_FB_A	T
N2	PL46B	6	LLM3_SPLLC_FB_A	C
VCCIO	VCCIO6	6		
GNDIO	GNDIO6	-		
P6	PL52A	6	LDQS52****	T (LVDS)*
N5	PL52B	6	LDQ52	C (LVDS)*
P1	PL53A	6	LDQ52	T
VCCIO	VCCIO6	6		
P2	PL53B	6	LDQ52	C
P3	PL54A	6	LDQ52	T (LVDS)*
P4	PL54B	6	LDQ52	C (LVDS)*
P5	PL55A	6	LDQ52	T
GNDIO	GNDIO6	-		
P7	PL55B	6	LDQ52	C
VCCIO	VCCIO6	6		
GNDIO	GNDIO6	-		
R1	PL62A	6	LLM0_GPLLT_IN_A**	T (LVDS)*
GNDIO	GNDIO6	-		
R2	PL62B	6	LLM0_GPLLC_IN_A**	C (LVDS)*
R3	PL63A	6	LLM0_GPLLT_FB_A	T
R4	PL63B	6	LLM0_GPLLC_FB_A	C
VCCIO	VCCIO6	6		
R6	PL64A	6	LLM0_GDLLT_IN_A**	T (LVDS)*
R5	PL64B	6	LLM0_GDLLC_IN_A**	C (LVDS)*

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7	T
D3	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7	C
GNDIO	GNDIO7	-			GNDIO7	-		
J8	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*
H7	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*
E3	PL12A	7	LUM0_SPLLT_FB_A	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T
E4	PL12B	7	LUM0_SPLLC_FB_A	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C
GNDIO	GNDIO7	-			-	-		
G6	PL13A	7		T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*
F5	PL13B	7		C (LVDS)*	PL13B	7	LDQ15	C (LVDS)*
E2	PL14A	7		T	PL14A	7	LDQ15	T
D1	PL14B	7		C	PL14B	7	LDQ15	C
-	-	-			GNDIO7	-		
G5	NC	-			PL15A	7	LDQS15	T (LVDS)*
G4	NC	-			PL15B	7	LDQ15	C (LVDS)*
K7	NC	-			PL16A	7	LDQ15	T
K8	NC	-			PL16B	7	LDQ15	C
E1	NC	-			PL17A	7	LDQ15	T (LVDS)*
F2	NC	-			PL17B	7	LDQ15	C (LVDS)*
F1	NC	-			PL18A	7	LDQ15	T
-	-	-			GNDIO7	-		
G3	NC	-			PL18B	7	LDQ15	C
H5	PL15A	7		T (LVDS)*	PL21A	7		T (LVDS)*
H4	PL15B	7		C (LVDS)*	PL21B	7		C (LVDS)*
J5	PL16A	7		T	PL22A	7		T
J4	PL16B	7		C	PL22B	7		C
GNDIO	GNDIO7	-			GNDIO7	-		
G2	NC	-			PL24A	7	LDQ28	T (LVDS)*
G1	NC	-			PL24B	7	LDQ28	C (LVDS)*
L9	NC	-			PL25A	7	LDQ28	T
L7	NC	-			PL25B	7	LDQ28	C
K6	NC	-			PL26A	7	LDQ28	T (LVDS)*
K5	NC	-			PL26B	7	LDQ28	C (LVDS)*
L8	NC	-			PL27A	7	LDQ28	T
L6	NC	-			PL27B	7	LDQ28	C
-	-	-			GNDIO7	-		
H3	PL18A	7		T (LVDS)*	PL28A	7	LDQS28	T (LVDS)*
H2	PL18B	7		C (LVDS)*	PL28B	7	LDQ28	C (LVDS)*
N8	PL19A	7		T	PL29A	7	LDQ28	T
M9	PL19B	7		C	PL29B	7	LDQ28	C
J3	PL20A	7		T (LVDS)*	PL30A	7	LDQ28	T (LVDS)*
VCCIO	VCCIO7	7			-	-		
J2	PL20B	7		C (LVDS)*	PL30B	7	LDQ28	C (LVDS)*
H1	PL21A	7		T	PL31A	7	LDQ28	T
GNDIO	GNDIO7	-			GNDIO7	-		
J1	PL21B	7		C	PL31B	7	LDQ28	C
-	-	-			-	-		
-	-	-			-	-		

**LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA
 (Cont.)**

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AF17	GND	-			GND	-		
AF25	GND	-			GND	-		
AF6	GND	-			GND	-		
AJ10	GND	-			GND	-		
AJ21	GND	-			GND	-		
AJ27	GND	-			GND	-		
AJ4	GND	-			GND	-		
AK1	GND	-			GND	-		
AK13	GND	-			GND	-		
AK18	GND	-			GND	-		
AK24	GND	-			GND	-		
AK30	GND	-			GND	-		
AK7	GND	-			GND	-		
B10	GND	-			GND	-		
B21	GND	-			GND	-		
B27	GND	-			GND	-		
B4	GND	-			GND	-		
D25	GND	-			GND	-		
D6	GND	-			GND	-		
E14	GND	-			GND	-		
E17	GND	-			GND	-		
F22	GND	-			GND	-		
F27	GND	-			GND	-		
F4	GND	-			GND	-		
F9	GND	-			GND	-		
G12	GND	-			GND	-		
G19	GND	-			GND	-		
J24	GND	-			GND	-		
J7	GND	-			GND	-		
K14	GND	-			GND	-		
K15	GND	-			GND	-		
K16	GND	-			GND	-		
K17	GND	-			GND	-		
K27	GND	-			GND	-		
K4	GND	-			GND	-		
L14	GND	-			GND	-		
L15	GND	-			GND	-		
L16	GND	-			GND	-		
L17	GND	-			GND	-		
M23	GND	-			GND	-		
M8	GND	-			GND	-		
N14	GND	-			GND	-		
N15	GND	-			GND	-		
N16	GND	-			GND	-		
N17	GND	-			GND	-		
N27	GND	-			GND	-		
N4	GND	-			GND	-		
P11	GND	-			GND	-		

**LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA
 (Cont.)**

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
Y15	GND	-			GND	-		
Y16	GND	-			GND	-		
Y17	GND	-			GND	-		
AA26	NC	-			NC	-		
AB10	PL73B	6	LDQ71	C (LVDS)*	NC	-		
AB11	NC	-			NC	-		
AB12	NC	-			NC	-		
AB13	NC	-			NC	-		
AB14	NC	-			NC	-		
AB15	NC	-			NC	-		
AB16	NC	-			NC	-		
AB17	NC	-			NC	-		
AB19	NC	-			NC	-		
AB20	NC	-			NC	-		
AB21	NC	-			NC	-		
AB9	PL73A	6	LDQ71	T (LVDS)*	NC	-		
AC10	PL74B	6	LDQ71	C	NC	-		
AC11	NC	-			NC	-		
AC21	NC	-			NC	-		
AC22	NC	-			NC	-		
AC8	PL70B	6	LDQ71	C	NC	-		
AC9	PL74A	6	LDQ71	T	NC	-		
AD21	NC	-			NC	-		
AD22	NC	-			NC	-		
AD4	PL68A	6	LDQ71	T	NC	-		
AD5	PL68B	6	LDQ71	C	NC	-		
AD6	PL71A	6	LDQS71	T (LVDS)*	NC	-		
AD7	PL72A	6	LDQ71	T	NC	-		
AD8	PL72B	6	LDQ71	C	NC	-		
AE23	NC	-			NC	-		
AE5	PL69A	6	LDQ71	T (LVDS)*	NC	-		
AE6	PL70A	6	LDQ71	T	NC	-		
AE7	PL71B	6	LDQ71	C (LVDS)*	NC	-		
AF20	NC	-			NC	-		
AF23	NC	-			NC	-		
AF5	PL69B	6	LDQ71	C (LVDS)*	NC	-		
AG23	NC	-			NC	-		
AG26	NC	-			NC	-		
D10	PT10A	0		T	NC	-		
E10	PT9B	0		C	NC	-		
E11	PT10B	0		C	NC	-		
F10	PT9A	0		T	NC	-		
F20	NC	-			NC	-		
F23	NC	-			NC	-		
F8	PL6B	7	LDQ6	C (LVDS)*	NC	-		
G10	NC	-			NC	-		
G20	NC	-			NC	-		
G21	NC	-			NC	-		